

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	29	lau near daniel.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 17:45
L2	1	law near edwrard.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 17:46
L3	6	((heat) near (lid spreader)) with ((mold\$3) near (compound chase))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 17:50
L4	190	((heat) near (lid spreader)) with ((mold\$3) near (compound chase))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 17:56
L5	3	((heat) near (lid spreader)) with ((mold\$3) near (compound chase)) with (cut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 17:51
L6	108	((heat) near (lid spreader)) with ((mold\$3) near (compound chase)) with (die chip component ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 17:56
L7	39	((heat) near (lid spreader)) with ((mold\$3) near (compound chase)) with (die chip component ic) with (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:03
L8	88	((heat) near (lid spreader)) with ((mold\$3) near (compound chase)) same (die chip component ic) with (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:04
L9	13	((heat) near (lid spreader)) with (therma\$3) with ((mold\$3) near (compound chase)) same (die chip component ic) with (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:10

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L10	20	((heat) near (lid spreader)) with (therma\$3) with ((mold\$3) near (compound chase)) and (die chip component ic) with (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:11
L11	148	((heat) near (lid spreader)) with ((mold\$3) near (compound chase)) and (die chip component ic) with (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:12
L12	21	11 and ((heat) near (spreader lid)) with (align\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:22
L13	443	"5367196" "5608267" "5650663" "5905632" "5919329" "5970319" "5977626" "6057601" "6359341" "6409859" "6432742" "6432749" "6432752"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:23
L14	31	((heat lid) near (spreader)) with (mold\$3)) same (align\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:40
L15	519	((heat lid) near (spreader)) with (mold\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:40
L16	343	15 and (((heat lid) near (spreader)) with (thermal\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:12
L17	97	15 and (((heat lid) near (spreader)) with (thermal\$3 near2 conductivit\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:02
L18	0	15 and (((heat lid) near (spreader)) with (protrusion\$1) with (thermal\$3 near2 conductivit\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:59
L19	0	15 and (((heat lid) near (spreader)) same (protrusion\$1) with (thermal\$3 near2 conductivit\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 18:59

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L20	39	16 and (protrusion\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:00
L21	50	15 and (((heat lid) near (spreader)) with (thermal\$3 near2 conductivit\$3)) with (high\$3 low\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:03
L22	87	(substrate) with (metallic near lead near frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:12
L23	1	22 and (heat near spreader)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:13
L24	3	22 and (spreader)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:15
L25	474	((substrate) near10 (dielectric)) with (electrical near2 conductor\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:16
L26	10	((substrate) near10 (dielectric)) with (electrical near2 conductor\$1) with (trace\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:17
L27	160	((substrate) near10 (dielectric)) with (conductor\$1) with (trace\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:17
L28	46	((substrate) near10 (dielectric)) with (conductor\$1) with (conductive near2 trace\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:20
L29	0	((substrate) near10 (dielectric)) with (array near5 conductor\$1) with (conductive near2 trace\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:21

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L30	3	((substrate) near10 (dielectric)) with (array near5 conductor\$1) with (trace\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 19:21
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